

PATENT ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Lie-Yong Yang</td><td>04/13/2011</td></tr><tr><td>Sheng Chiang Hung</td><td>04/13/2011</td></tr><tr><td>Kian-Long Lim</td><td>04/13/2011</td></tr></tbody></table>	Name	Execution Date	Lie-Yong Yang	04/13/2011	Sheng Chiang Hung	04/13/2011	Kian-Long Lim	04/13/2011	
Name	Execution Date								
Lie-Yong Yang	04/13/2011								
Sheng Chiang Hung	04/13/2011								
Kian-Long Lim	04/13/2011								
RECEIVING PARTY DATA									
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.								
Street Address:	No. 8, Li-Hsin Road 6								
City:	Hsin-Chu								
State/Country:	TAIWAN								
Postal Code:	300-77								
PROPERTY NUMBERS Total: 1									
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>13087016</td></tr></tbody></table>	Property Type	Number	Application Number:	13087016					
Property Type	Number								
Application Number:	13087016								
CORRESPONDENCE DATA									
Fax Number: (214)200-0853 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
Phone: 214-651-5000									
Email: ipdocketing@haynesboone.com									
Correspondent Name: HAYNES AND BOONE, LLP									
Address Line 1: 2323 Victory Avenue									
Address Line 2: Suite 700									
Address Line 4: Dallas, TEXAS 75219									
ATTORNEY DOCKET NUMBER:	24061.1717 - RACHEL DAVIS								
NAME OF SUBMITTER:	Rachel L.I. Davis								
Total Attachments: 3 source=1717_Assignment#page1.tif source=1717_Assignment#page2.tif source=1717_Assignment#page3.tif									

OP \$40.00 13087016

501501295

PATENT
REEL: 026128 FRAME: 0660

ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|-------------------|----|---|
| (1) | Lie-Yong Yang | of | 8, Li-Hsin Road 6, SBIP
Hsinchu 300-77, Taiwan, R.O.C. |
| (2) | Sheng Chiang Hung | of | 6F-1, No. 60, Lyushuei Road
Hsinchu City 300, Taiwan, R.O.C. |
| (3) | Kian-Long Lim | of | Room A, 9F, No. 20, Alley 53, Lane 2, Jinshan 11st St., East District
Hsinchu City 300, Taiwan, R.O.C. |
| (4) | Ping-Wei Wang | of | 9F, No. 22, Lane 23, Jian-Zhong 1st Road
Hsin-Chu, Taiwan, R.O.C. |

have invented certain improvements in

DIVOT ENGINEERING FOR ENHANCED DEVICE PERFORMANCE

for which we have executed an application for Letters Patent of the United States of America, filed on 04-14-2011 and assigned application number 13/087,016; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

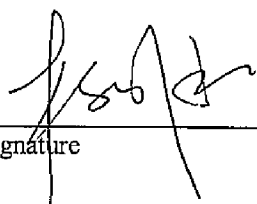
AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional,

continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Lie-Yong Yang

Residence Address: 8, Li-Hsin Road 6, SBIP
Hsinchu 300-77, Taiwan, R.O.C.

Dated: ✓ 13/04/2011

✓ 
Inventor Signature

Inventor Name: Sheng Chiang Hung

Residence Address: 6F-1, No. 60, Lyushuei Road
Hsinchu City 300, Taiwan, R.O.C.

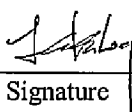
Dated: ✓ 13/04/2011

✓ 洪聖強
Inventor Signature

Inventor Name: Kian-Long Lim

Residence Address: Room A, 9F, No. 20, Alley 53, Lane 2, Jinshan 11st St., East District
Hsinchu City 300, Taiwan, R.O.C.

Dated: ✓ 13/04/2011

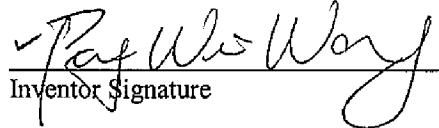
✓ 
Inventor Signature

Docket No.: 2010-1311 / 24061.1717
Customer No.: 42717

Inventor Name: Ping-Wei Wang

Residence Address: 9F, No. 22, Lane 23, Jian-Zhong 1st Road
Hsin-Chu, Taiwan, R.O.C.

Dated: ✓ 13/04/2011


Inventor Signature